EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	(adhe$3 and molecular and compound and electronic and (contact pad electrode) and bond$3 and hydrocarbon and polymer and coat$3).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/27 14:12
L2	3	(electronic and compound and interface and plural$3 and array and hydrocarbon and polymer and electronic with (component device)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/27 14:19
L3	199	moriceau.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/27 14:21
L4	3	3 and hydrocarbon with polymer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/27 14:21
L5	3450	438/118	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/27 15:04
L6	2231	438/109	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/27 15:04
L7	2850	438/455	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/27 15:04
L8	7804	5 6 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/27 15:04

L9	234	8 and hydrocarbon	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/27 15:04
L11	36	9 and bond$3 and hydrocarbon with polymer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/27 15:05
L12	1867	257/685	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/27 15:07
L13	5215	257/723	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/27 15:07
L14	6028	12 13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/27 15:07
L15	2	14 and bond$3 and hydrocarbon with polymer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/27 15:07
L16	7	257/E21.128	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/27 15:11
L17	0	(electronic and compound and interface and (contact pad surface) and hydrocarbon and polymer and silicon with (oxide nitride ox$1nitride) and cross$1link$1 and (polish$3 activat$3)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/27 15:37

L18	0	(component and interface and (contact pad surface) and hydrocarbon and polymer and silicon with (oxide nitride ox $1nitride) and cross $1link$1 and (polish$3 activat$3)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/27 15:38
S4	99	"4983251"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/13 13:14
S5	2	("4983251").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/02/13 13:26
S6	5	"2003021705"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/13 13:27
S7	3	"20030211705"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/13 13:28
S8	17430	(Bond$3 adhes$3) with silicon with oxide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/13 13:55
S9	3764	(Bond$3 adhes$3) with silicon with oxide and stack$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/13 13:56
S10	2624	(Bond$3 adhes$3) with silicon with oxide and stack$3 and heat $3 and (thin$4 CMP etch$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/13 13:56
S12	83	(Bond$3 adhes$3) with silicon with oxide and stack$3 and heat $3 and (thin$4 CMP etch$3) and clean$3 and polymer with cross $1link$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/13 13:58

S13	16	(Bond$3 adhes$3) with silicon with oxide and stack$3 and heat $3 and (planneriz$3 thin$4 CMP etch$3) with (cross$link$3) and clean$3 and polymer and cross $1link$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/13 19:20
S14	3245	438/118	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/13 20:50
S15	10	S14 and silicon with oxide with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/13 20:51
S16	11	438/406 and silicon with oxide with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/13 20:52
S17	1261	(Bond$3 adhes$3) with silicon with oxide and stack$3 and heat $3 and (thin$4 CMP etch$3) and clean$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/15 15:05
S18	460	bond$3 and adhe$4 and hydrocarbon with polymer and hydrocarbon with bond $3 and (contact pad electrode) with bond$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/26 10:31
S19	42	molecular with adhes $3 and coat$3 with (contact pad electrode) and compound and bond$3 with hydrocarbon with polymer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/26 18:01
S20	220797	"438"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/26 18:01
S21	428986	"257"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/26 18:01

S22	502279	S20 S21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/26 18:01
S23	3	S19 and S22	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/26 18:01
S24	76	array with (stack$3 three with dimensional) and interface with hydrocarbon	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/26 18:07
S25	3	"2003211705"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/26 18:11
S26	3	"2003211705"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/26 18:11
S27	17	"4963251"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/26 18:11
S28	107	"4983251"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/26 18:12
S30	34	S28 and array	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/26 18:13
S31	4	S28 and hydrocarbon	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/26 18:14

8/27/2008 3:38:42 PM
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